

## P-Channel 80V(D-S) MOSFET

Product summary		
$V_{DS}$	-80	V
$R_{DS(ON)}$ (at $V_{GS}=-10V$ ) Typ.	14	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ ) Typ.	17	$m\Omega$
$I_D(T_c=25^\circ C)$	-50	A

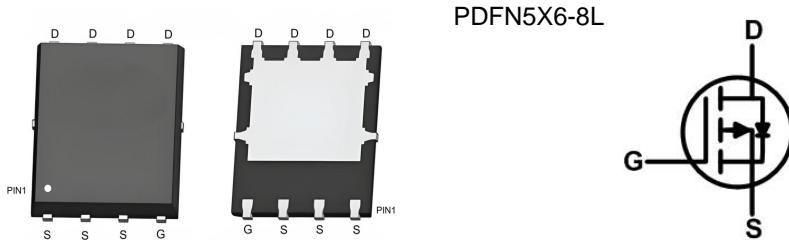
### Features

- Split gate trench MOSFET technology
- Low  $R_{DS(ON)}$
- Excellent stability and uniformity

### Applications

- Portable equipment
- Power Management

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP50P08A	PDFN5X6-8L	13"	5000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-80	V
$V_{GS}$	Gate-Source Voltage	$\pm 18$	V
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	-200	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	600	mJ
$P_D$	Power Dissipation <sup>C</sup>	$T_c=25^\circ C$	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{eJC}$	Thermal Resistance-Junction to case max	1.2	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-80	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-80\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 18\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	-2.1	-3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>D</sup>	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-25\text{A}$	--	14	18	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-20\text{A}$	--	17	23	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=-25\text{A}, V_{\text{GS}}=0\text{V}$	--	--	-1.2	V
$R_{\text{G}}$	Gate resistance	$f=1\text{MHz}$	--	8	--	$\Omega$
$I_{\text{S}}$	Maximum Body-Diode Continuous Current		--	--	-50	A
Dynamic Parameters <sup>E</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-40\text{V}$ $f=1\text{MHz}$	--	5300	--	pF
$C_{\text{oss}}$	Output Capacitance		--	490	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	47	--	pF
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{DS}}=-40\text{V}, I_{\text{D}}=-25\text{A}$ $V_{\text{GS}}=-10\text{V}$	--	90	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	25	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	16	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-40\text{V}$ $, V_{\text{GS}}=-10\text{V}$ $R_{\text{GEN}}=3\Omega$ $I_{\text{D}}=-25\text{A}$	--	14	--	ns
$t_{\text{r}}$	Turn-on Rise Time		--	81	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	135	--	ns
$t_{\text{f}}$	Turn-off Fall Time		--	84	--	ns
$t_{\text{rr}}$	Reverse recovery time	$I_{\text{F}}=-25\text{A}$ $di/dt=100 \text{ A/uS}$	--	63	--	ns
$Q_{\text{rr}}$	Reverse recovery charge		--	125	--	nC

Note:

- A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- B. EAS condition:  $T_J=25^\circ\text{C}$ ,  $R_G=25\Omega$ ,  $V_{\text{DD}}=-50\text{V}$ ,  $V_{\text{G}}=-10\text{V}$ ,  $L=0.3\text{mH}$ ,  $I_{\text{AS}}=-20\text{A}$ .
- C.  $P_D$  is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.
- D. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .
- E. Guaranteed by design, not subject to production testing.

## Typical Characteristics

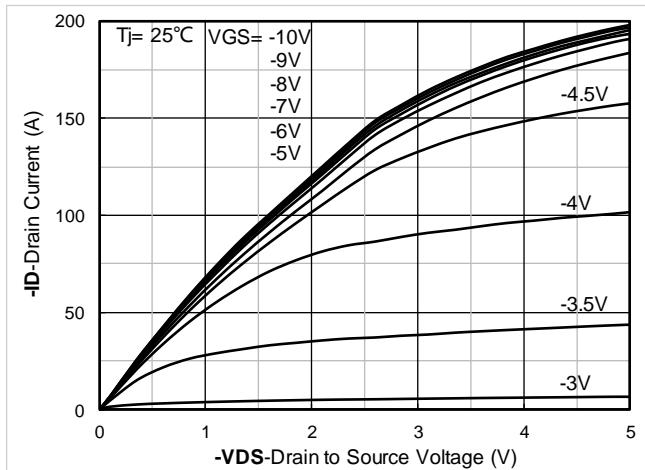


Figure 1. Output Characteristics

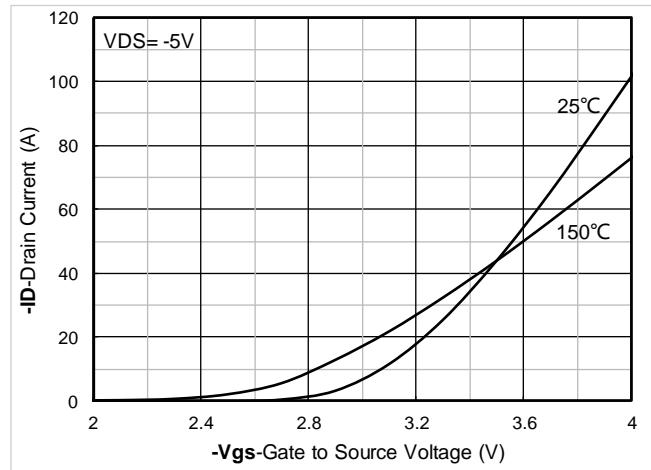


Figure 2. Transfer Characteristics

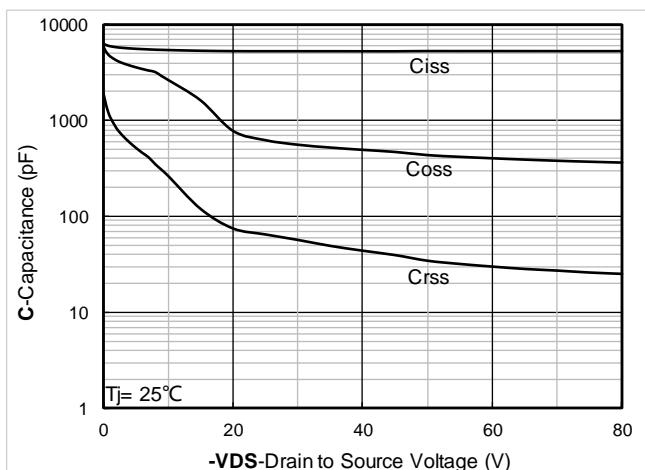


Figure 3. Capacitance Characteristics

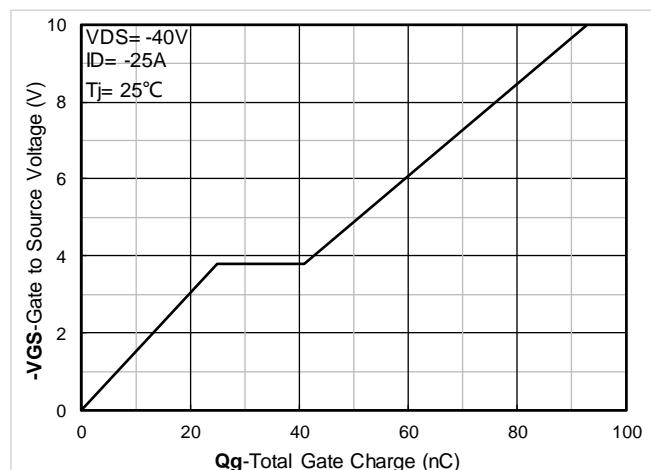


Figure 4. Gate Charge

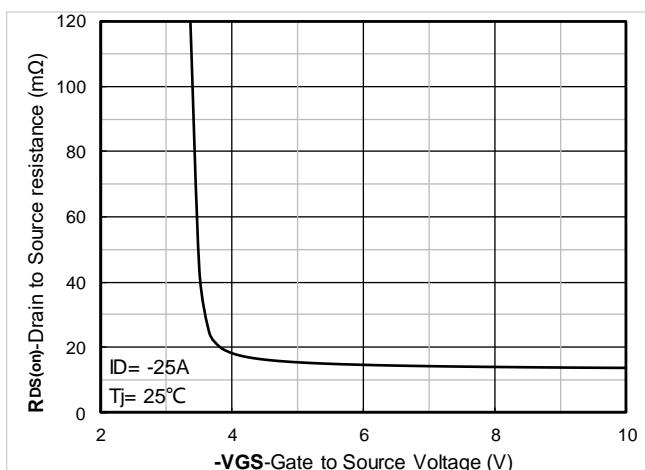


Figure 5. On-Resistance vs Gate to Source Voltage

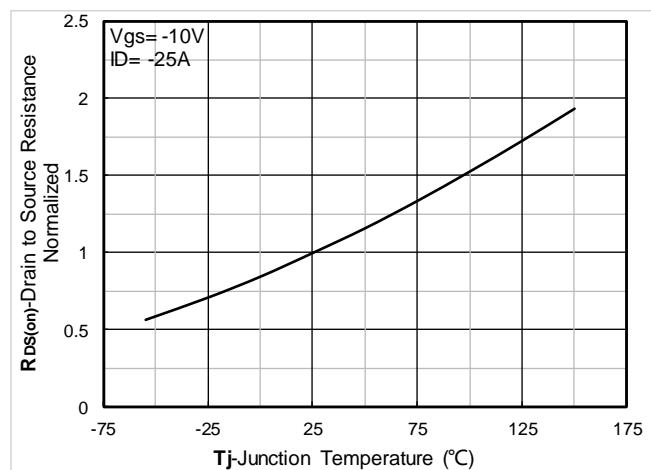
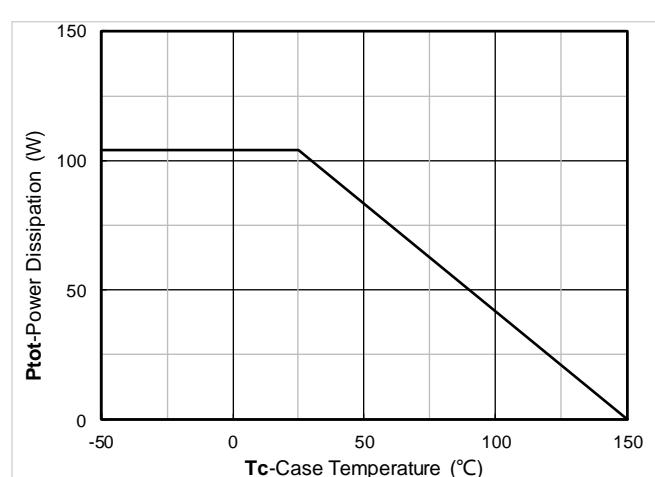
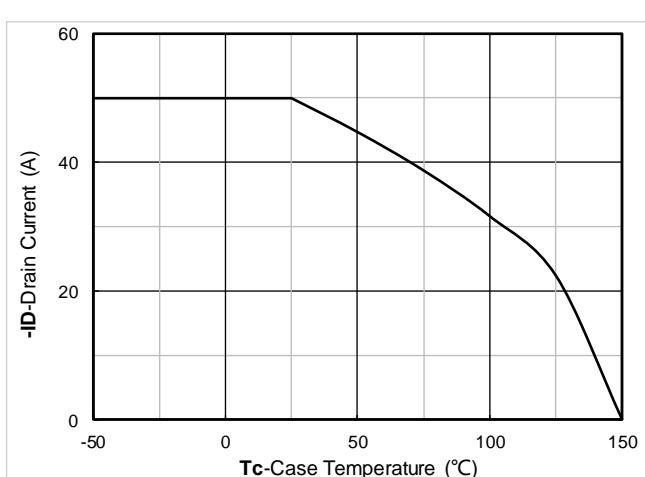
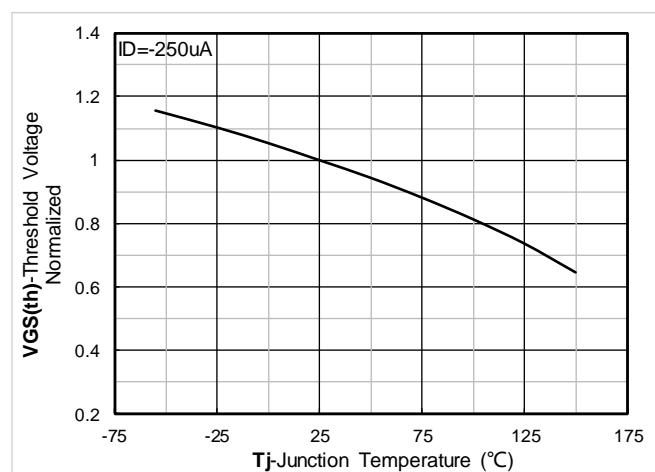
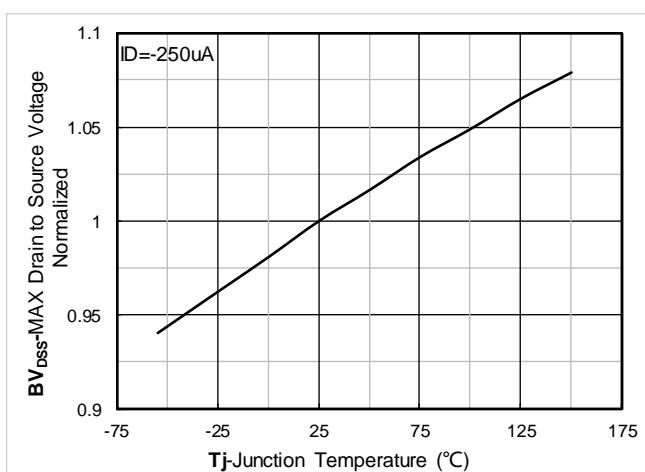
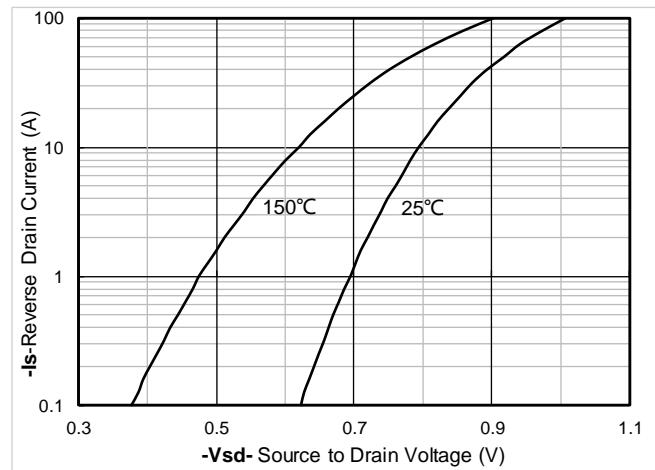
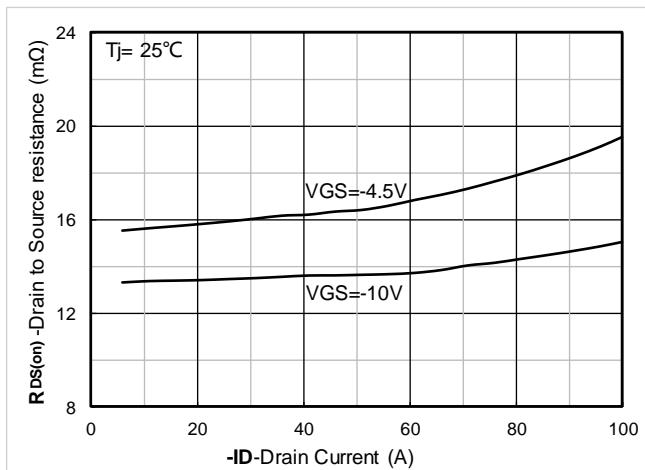


Figure 6. Normalized On-Resistance

## Typical Characteristics



## Typical Characteristics

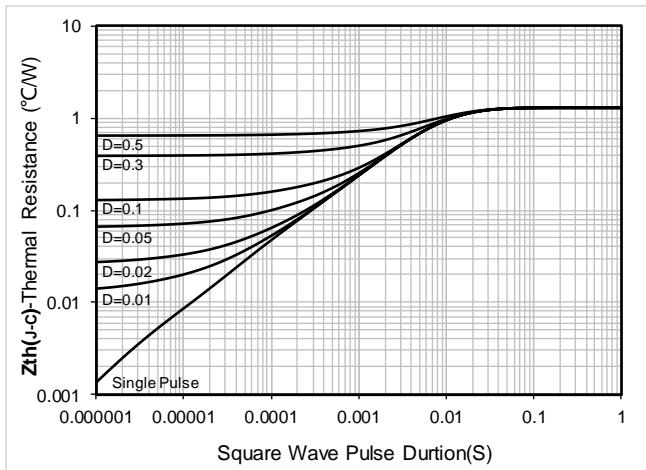


Figure 13. Maximum Transient Thermal Impedance

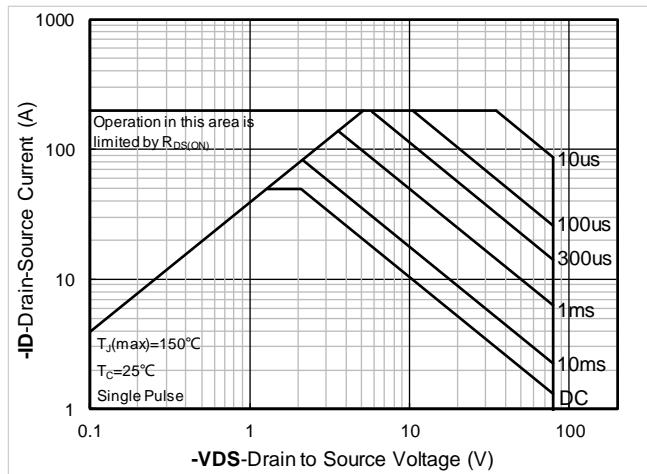
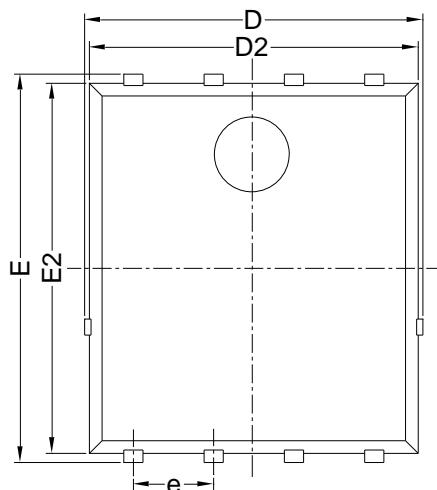
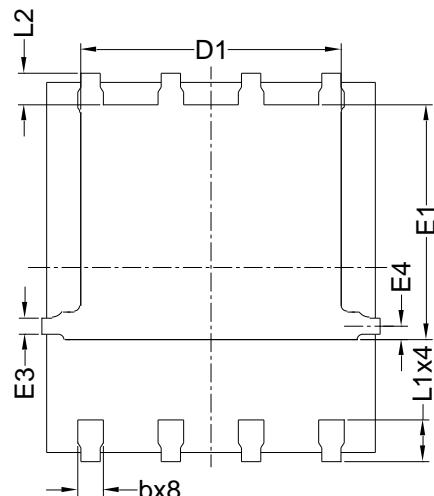


Figure 14. Safe Operation Area

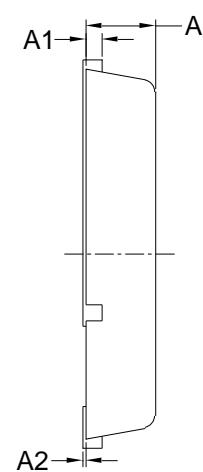
## PDFN5X6-8L Package Information (unit:mm)



Top View  
正面视图



Bottom View  
背面视图



Side View  
侧面视图

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254 REF		
E4	0.21 REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension:in millimeters.
2. General tolerance: $\pm 0.10\text{mm}$ .
3. The pad layout is for reference purposes only.